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NATIONAL STANDARD OF THE

PEOPLE'S REPUBLIC OF CHINA

GB/T 19247.1-2026

Replacing GB/T 19247.1-2003

Printed board assemblies - Part 1: Generic specification - Requirements for soldered electrical and electronic assemblies using surface mount and related assembly technologies

印制板组装 第1部分：通用规范 采用表面安装和相关组装技术的电子和电气焊接组装的要求

(English Translation)

Issued on: September 28, 2026

Issued by: State Administration for Market Regulation;
Standardization Administration of China

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https://chinastandards.org/standards/gb-t-19247-1-2026

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1 Foreword

GB/T 19247.1-2026 was issued by State Administration for Market Regulation; Standardization Administration of China on 28 September 2026.

It replaces the earlier edition GB/T 19247.1-2003.

It is one of 8 parts of the GB/T 19247 series.

2 Scope Preview

GB/T 19247.1-2026 carries no ICS number and no Chinese Standard Classification code.

This catalogue holds 76,457 other GB/T standards.

Of the 47,415 GB/T standards that do carry an ICS number, 3,437 (7%) fall under ICS 77, in the field of metallurgy.

3 About this standard

Issued by: State Administration for Market Regulation; Standardization Administration of China

4 Related standards

Other parts of this standard:

GB/T 19247.2-2003 - Printed board assemblies -- Part 2: Sectional specification -- Requirements for surface mount soldered assemblies

GB/T 19247.2-2026 - 2: Sectional specification - Requirements for surface mount soldered assemblies

GB/T 19247.3-2003 - Printed board assemblies -- Part 3: Sectional specification --

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Requirements for through-hole mount soldered assemblies

GB/T 19247.3-2026 - 3: Sectional specification - Requirements for through-hole mount soldered assemblies

GB/T 19247.4-2003 - Printed board assemblies -- Part 4: Sectional specification -- Requirements for terminal soldered assemblies

GB/T 19247.4-2026 - 4: Sectional specification - Requirements for terminal soldered assemblies

GB/T 19247.6-2024 - 6: Evaluation criteria for voids in soldered joints of BGA and LGA and measurement method

Other editions:

GB/T 19247.1-2003 (earlier edition)

5 Classification and status

Prefix GB/T: recommended standard.

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